



Material Content Data Sheet



Halogen-Free

Sales Product Name	TLE8088EM	Issued	25. June 2021
MA#	MA005560581		
Package	PG-SSOP-24-9	Weight*	150.39 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.532	1.68	1.68	16837	16837
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		112	
	non noble metal	zinc	7440-66-6	0.067	0.04		447	
	non noble metal	iron	7439-89-6	1.345	0.89		8944	
	non noble metal	copper	7440-50-8	54.617	36.32	37.26	363160	372663
wire	non noble metal	copper	7440-50-8	0.478	0.32	0.32	3176	3176
encapsulation	organic material	carbon black	1333-86-4	0.175	0.12		1162	
	plastics	epoxy resin	-	8.038	5.34		53449	
	inorganic material	silicondioxide	60676-86-0	79.160	52.63	58.09	526352	580963
leadfinish	non noble metal	tin	7440-31-5	2.911	1.94	1.94	19355	19355
plating	noble metal	silver	7440-22-4	0.234	0.16	0.16	1558	1558
glue	plastics	epoxy resin	-	0.205	0.14		1362	
	noble metal	silver	7440-22-4	0.615	0.41	0.55	4086	5448
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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